



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2815
#5/A
1/6/03
Mollin

In re the Application of:

Baldonado, et al.

Docket No.: TI-32857

Serial No.: 10/066,421 ✓

Examiner: Clark, S.V.

Filed: 01/30/02 ✓

Art Unit: 2815

For: Method and System of Wire Bonding Using Interposer Pads

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited
with the U.S. Postal Service as First Class Mail in an
envelope addressed to: Assistant Commissioner for Patents,
Washington, D.C. 20231 on

11-29-02

Michael K. Skrehot

Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 08/28/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

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